

**NONPROVISIONAL PATENT
APPLICATION TRANSMITTAL RULE §1.53(b)
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Customer No. 004372
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Docket No. 103203-00008

Date: October 31, 2003

Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmitted herewith for filing under 37 C.F.R. §1.53(b) is a nonprovisional patent application:

For (Title): Ultra-Thin Copper Foil With Carrier, Method of Production of Same, And
Printed Circuit Board Using Ultra-Thin Copper Foil With Carrier

By (Inventors): Yuuji SUZUKI and Akira MATSUDA

- ☒ Sixty-Four (64) pages of Specification/Claims 1-29/Abstract are attached.
☒ Formal drawings (Fig(s). 1-4; Four (4) sheet(s)) is/are attached.
☒ Priority of foreign application No. 2002-317907 filed October 31, 2002 in Japan is claimed under 35 U.S.C. §119.
☒ A certified copy of the above corresponding foreign application is attached.

The filing fee is calculated below and includes claim status after entry of any Preliminary Amendment noted above:

FOR:	NO. FILED	NO. EXTRA
BASIC FEE		
TOTAL CLAIMS	104 - 20	= 84
INDEP CLAIMS	14 - 3	= 11
<input checked="" type="checkbox"/> MULTIPLE DEPENDENT CLAIMS		

SMALL ENTITY			LARGE ENTITY	
RATE	FEE	OR	RATE	FEE
	\$ 385	OR		\$ 770
x 9 =	\$	OR	x 18	\$ 1512
x 43 =	\$	OR	x 86	\$ 473
+145 =	\$	OR	+290	\$ 290
TOTAL	\$	OR	TOTAL	\$ 3,045

- ☒ A check for the filing fee is not enclosed at this time.

Respectfully submitted,


Charles M. Markelstein
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CMM:jns